1. (Amended) A semiconductor device assembly, comprising:

a semiconductor die having an active surface having a plurality of bond pads thereon and an opposing second surface;

at least one projection connected to at least one bond pad of said plurality of bond pads on the active surface of said semiconductor die for direct connection to a substrate, said at least one projection including one of at least one solder ball and at least one solder bump; and

a paddle of a lead frame of a plurality of lead frames having side rails connected to said paddle, said second surface of said semiconductor die secured to said paddle.

14. (Amended) A semiconductor device assembly, comprising:

a semiconductor die having an active surface having at least one bond pad thereon and an opposing second surface;

at least one projection secured to said at least one bond pad on said active surface of said semiconductor die for direct connection to a substrate, said at least one projection including one of at least one solder ball and at least one solder bump; and

a metal paddle from a lead frame, said second surface of said semiconductor die attached to said metal paddle.

20. (Amended) The semiconductor device assembly of claim 14, further comprising:

an electrically conductive adhesive layer attaching said second surface to said metal paddle.

27. (Amended) A semiconductor device assembly, comprising:

a semiconductor die having an active surface having a plurality of bond pads thereon and an opposing second surface;

a plurality of projections connected to said plurality of bond pads for direct connection to a host circuit board, said plurality of projections including one of a plurality of solder balls and a plurality of solder bumps; and

a metallic paddle secured to said second surface of said semiconductor die.